# **Technical Datasheet** Elecolit® 3648



#### **Product Description**

Modified epoxy | 1 part | solvent-free | thermal-curing | thermally conductive | electrically conductive

Die attach

Conductive bonding

Very flexible

Snap cure; curing with thermode possible

#### **Curing Properties**

This adhesive can be cured with heat. Typical curing temperatures are listed in the table below.

| Temperatures | Time   |
|--------------|--------|
| 80°C         | 30 min |
| 90°C         | 15 min |
| 100°C        | 5 min  |
| 115°C        | 25 sec |

The curing times given are guidelines. They refer to rheological measurements according to PE-Norm 067. The heating times of the parts to be joined are not taken into account. Actual cure times can vary based on part size, configuration, adhesive volume, temperature control, and the time required for the component substrates to attain oven temperature.

The final bond strength of the adhesive is achieved no sooner than 24 h after the bonded components are removed from the oven.

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# Elecolit® 3648



| Resin  | Technical Data  |                 |
|--|---|-----------------|
| Appearance   Grey   Filler   Silver   S |   |                 |
| Filler   Silver   Sil |   |                 |
| Filler - weight [%]   80     Particle size D90 [µm]   21.8     Uncured Material     Viscosity [mPas] (Kinexus Rheometer, 25 °C, 10s¹)   10,000 – 15,000     PE-Norm 064   10,000 – 15,000     PE-Norm 064   3.9 – 4     PE-Norm 064   3.9 – 4     Working life [h]   6     PE-Norm 004   8     Working life [h]   6     PE-Norm 006   50 – 60     PE-Norm 006   50 – 60     PE-Norm 006   70 – 60     PE-Norm 006   70 – 70     PE-Norm 006   70 – 70     PE-Norm 007   70 – 70     Coefficient of thermal expansion [ppm/K] below Tg   115°C, 30min   40 – 50     PE-Norm 017   70 – 70     PE-Norm 018   70 – 70     PE-Norm 019   70 – 70     PE-Norm 02   70 – 70     PE-Norm 03   70 – 70     PE-Norm 04   70 – 70     PE-Norm 05   70 –    |   |                 |
| Particle size D90 [µm]   21.8  |   |                 |
| Uncured Material           Viscosity [mPas] (Kinexus Rheometer, 25 °C, 10s²)         10,000 − 15,000           pE-Norm 064         2 − 3           Thixotropic index [1/10]         3.9 − 4           pE-Norm 064         3.9 − 4           Working life [h]         48           @ room temperature         48           Cured Material         48           Hardness shore D         115°C, 30min         50 − 60           pE-Norm 006         −40 − 180           Temperature resistance [°C]         -40 − 180           Shrinkage [%]         <0.5   |   |                 |
| Viscosity [mPas] (Kinexus Rheometer, 25 °C, 10s¹)         10,000 − 15,000           PE-Norm 064         2 − 3           Density [g/cm³]         3.9 − 4           PE-Norm 004         48           Working life [h]         48           @ room temperature         50 − 60           Cured Material         115°C, 30min           Hardness shore D         115°C, 30min           PE-Norm 006         50 − 60           Temperature resistance [°C]         -40 − 180           Shrinkage [%]         <0.5   | Particle size D90 [μm]  | 21.8            |
| ### PE-Norm 064  Thixotropic index [1/10]  ### PE-Norm 064  Density [g/cm³]  ### PE-Norm 004  Working life [h]  ### or nom temperature    Cured Material   | Uncured Material  |                 |
| ### PE-Norm 064    Density [g/cm²]   | Viscosity [mPas] (Kinexus Rheometer, 25 °C, 10s <sup>-1</sup> ) | 10 000 – 15 000 |
| PE-Norm 064       2-3         Density [g/cm³]       3.9-4         PE-Norm 004       48         Working life [h]       48         © room temperature       48         Cured Material       50-60         Hardness shore D       115°C, 30min       50-60         PE-Norm 006       -40-180         Shrinkage [%]       <0.5   |   | 10,000 - 13,000 |
| DENSITY [g/cm²]   3.9 - 4     DENSITY [g/cm²]   3.9 - 4     DENSITY [g/cm²]   48     Or nom temperature  | •   | 2 – 3           |
| ## PE-Norm 004    Working life [h]   |   | _               |
| Working life [h]       48         @ room temperature       48         Cured Material       50 − 60         Hardness shore D       50 − 60         115°C, 30min       50 − 60         PE-Norm 006       -40 − 180         Shrinkage [%]       <0.5  | _ · -   | 3.9 – 4         |
| ### Cured Material  ### Hardness shore D  ### 15°C, 30min  ### 20.5  ### 20. |   |                 |
| Cured Material   Hardness shore D   115°C, 30min   50 – 60     PE-Norm 006   |   | 48              |
| Hardness shore D  115°C, 30min PE-Norm 006  Temperature resistance [°C]  Shrinkage [%]  115°C, 30min Vater absorption [%]  115°C, 30min PE-Norm 016  Glass transition temperature - DSC [°C]  115°C, 30min PE-Norm 019  Coefficient of thermal expansion [ppm/K] below Tg 115°C, 30min PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg 115°C, 30min PE-Norm 017  Thermal conductivity [W/m*K] 115°C, 30min PE-Norm 017  Thermal conductivity [W/m*K] 115°C, 30min PE-Norm 062  Volume resistivity [Ohm*cm] 115°C, 30min 1 - 3E-4 PE-Norm 040  Young's modulus – DMA [MPa] 115°C, 30min 300 – 400  |   |                 |
| 115°C, 30min   |   |                 |
| Temperature resistance [°C] -40 – 180  Shrinkage [%] 115°C, 30min  |   | 50 – 60         |
| Shrinkage [%]  115°C, 30min  PE-Norm 031  Water absorption [%]  115°C, 30min  PE-Norm 016  Glass transition temperature - DSC [°C]  115°C, 30min  PE-Norm 009  Coefficient of thermal expansion [ppm/K] below Tg  115°C, 30min  PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg  115°C, 30min  PE-Norm 017  Thermal conductivity [W/m*K]  115°C, 30min  PE-Norm 062  Volume resistivity [Ohm*cm]  115°C, 30min  PE-Norm 062  Young's modulus – DMA [MPa]  115°C, 30min  900 – 400   |   |                 |
| 115°C, 30min   | Temperature resistance [°C]                                     | -40 – 180       |
| Water absorption [%]  115°C, 30min PE-Norm 016  Glass transition temperature - DSC [°C]  115°C, 30min PE-Norm 009  Coefficient of thermal expansion [ppm/K] below Tg 115°C, 30min PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg 115°C, 30min PE-Norm 017  Thermal conductivity [W/m*K] 115°C, 30min PE-Norm 062  Volume resistivity [Ohm*cm] 115°C, 30min PE-Norm 040  Young's modulus – DMA [MPa] 115°C, 30min 300 – 400   | Shrinkage [%]   |                 |
| Water absorption [%]  115°C, 30min  PE-Norm 016  Glass transition temperature - DSC [°C]  115°C, 30min  PE-Norm 009  Coefficient of thermal expansion [ppm/K] below Tg  115°C, 30min  PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg  115°C, 30min  PE-Norm 017  Thermal conductivity [W/m*K]  115°C, 30min  PE-Norm 062  Volume resistivity [Ohm*cm]  115°C, 30min  PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400   |   | <0.5            |
| Glass transition temperature - DSC [°C]  115°C, 30min PE-Norm 009  Coefficient of thermal expansion [ppm/K] below Tg 115°C, 30min PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg 115°C, 30min PE-Norm 017  Thermal conductivity [W/m*K] 115°C, 30min PE-Norm 062  Volume resistivity [Ohm*cm] 115°C, 30min 1 - 3E-4 PE-Norm 040  Young's modulus – DMA [MPa] 115°C, 30min 300 – 400  |   |                 |
| Glass transition temperature - DSC [°C]  115°C, 30min  PE-Norm 009  Coefficient of thermal expansion [ppm/K] below Tg  115°C, 30min  PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg  115°C, 30min  PE-Norm 017  Thermal conductivity [W/m*K]  115°C, 30min  PE-Norm 062  Volume resistivity [Ohm*cm]  115°C, 30min  1 – 3E-4  PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400  |   | <1              |
| Glass transition temperature - DSC [°C]  115°C, 30min  PE-Norm 009  Coefficient of thermal expansion [ppm/K] below Tg  115°C, 30min  PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg  115°C, 30min  PE-Norm 017  Thermal conductivity [W/m*K]  115°C, 30min  PE-Norm 062  Volume resistivity [Ohm*cm]  115°C, 30min  PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400  |   | 1               |
| 115°C, 30min PE-Norm 009  Coefficient of thermal expansion [ppm/K] below Tg 115°C, 30min PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg 115°C, 30min PE-Norm 017  Thermal conductivity [W/m*K] 115°C, 30min PE-Norm 062  Volume resistivity [Ohm*cm] 115°C, 30min PE-Norm 040  Young's modulus – DMA [MPa] 115°C, 30min 300 – 400  |   |                 |
| Coefficient of thermal expansion [ppm/K] below Tg  115°C, 30min  PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg  115°C, 30min  PE-Norm 017  Thermal conductivity [W/m*K]  115°C, 30min  PE-Norm 062  Volume resistivity [Ohm*cm]  115°C, 30min  1 – 3E-4  PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400  | ·   | -10 – 20        |
| 115°C, 30min PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg 115°C, 30min PE-Norm 017  Thermal conductivity [W/m*K] 115°C, 30min PE-Norm 062  Volume resistivity [Ohm*cm] 115°C, 30min PE-Norm 040  Young's modulus – DMA [MPa] 115°C, 30min 300 – 400  |   |                 |
| 115°C, 30min PE-Norm 017  Coefficient of thermal expansion [ppm/K] above Tg 115°C, 30min PE-Norm 017  Thermal conductivity [W/m*K] 115°C, 30min PE-Norm 062  Volume resistivity [Ohm*cm] 115°C, 30min PE-Norm 040  Young's modulus – DMA [MPa] 115°C, 30min 300 – 400  |   |                 |
| Coefficient of thermal expansion [ppm/K] above Tg  115°C, 30min  PE-Norm 017  Thermal conductivity [W/m*K]  115°C, 30min  PE-Norm 062  Volume resistivity [Ohm*cm]  115°C, 30min  PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400  |   | 40 – 50         |
| 115°C, 30min PE-Norm 017  Thermal conductivity [W/m*K] 115°C, 30min PE-Norm 062  Volume resistivity [Ohm*cm] 115°C, 30min PE-Norm 040  Young's modulus – DMA [MPa] 115°C, 30min 300 – 400  |   |                 |
| Thermal conductivity [W/m*K]  115°C, 30min  PE-Norm 062  Volume resistivity [Ohm*cm]  115°C, 30min  PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400  |   | 190 200         |
| Thermal conductivity [W/m*K]  115°C, 30min  PE-Norm 062  Volume resistivity [Ohm*cm]  115°C, 30min  PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400  |   | 180 – 200       |
| 115°C, 30min PE-Norm 062  Volume resistivity [Ohm*cm] 115°C, 30min PE-Norm 040  Young's modulus – DMA [MPa] 115°C, 30min 300 – 400   |   |                 |
| PE-Norm 062  Volume resistivity [Ohm*cm]  115°C, 30min  PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400  | ,   |                 |
| Volume resistivity [Ohm*cm]  115°C, 30min  PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400   |   | 3 – 4           |
| 115°C, 30min PE-Norm 040  Young's modulus – DMA [MPa] 115°C, 30min 300 – 400   |   |                 |
| PE-Norm 040  Young's modulus – DMA [MPa]  115°C, 30min  300 – 400  | · ·   | 1 – 3E-4        |
| 115°C, 30min 300 – 400   |   |                 |
| 115°C, 30min 300 – 400   | Young's modulus – DMA [MPa]                                     |                 |
|  |   | 300 – 400       |
|  |   |                 |

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#### **Transport/Storage/Shelf Life**

| Package type      | Transport  | Storage    | Shelf life*                      |
|-------------------|------------|------------|----------------------------------|
| Syringe/Cartridge | 0°C 10°C   | 0°C – 10°C | At delivery                      |
| Other packages    | 0°C – 10°C |            | min. 1.5 months<br>max. 3 months |

<sup>\*</sup>Store in original, unopened containers!

#### **Instructions for use**

#### **Surface preparation**

The surfaces to be bonded should be free of dust, oil, grease, mold release, or other contaminants in order to obtain an optimal and reproducible bond. For cleaning we recommend the cleaner IP® from Panacol, or a solution of Isopropyl Alcohol at 90% or higher concentration. Substrates with low surface energy (e.g. polyethylene, polypropylene) must be pretreated in order to achieve sufficient adhesion.

#### **Application**

Our products are supplied ready to use. Depending on the packaging, our adhesives may be dispensed by hand directly from the package, or they can be applied using dispensing systems and automation. Many commercially available valve and controller options are available to ensure accurate and consistent adhesive dispensing. For assistance with dispensing and curing questions, please contact our Applications Engineering department. Adhesive and substrate should not be cold for proper bonding. They must be allowed to warm to room temperature prior to processing. After curing, the adhesive must be allowed to cool to ambient temperature before testing the product's performance. For safety information refer to our Material Safety Data Sheet (MSDS).

#### **Storage**

Store uncured product in its original, closed container in a dry location. Any material removed from the original container must not be returned to the container as it could be contaminated. Panacol cannot assume responsibility for products that were improperly stored, contaminated, or repackaged into other containers.

#### Handling and Clean-up

For safe handling information, consult this product's Material Safety Data Sheet (MSDS) prior to use. Uncured material may be wiped away from surfaces with organic solvents. Do not use solvents to remove material from eyes or skin!

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#### **Disclaimer**

The product is free of heavy metals, PFOS and Phthalates and is conform to the current EU-Directive RoHS.

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